Dear Mr. Otto and members of the OIF,

Thank you for your liaison letter providing the status of the OIF CEI-112G-VSR-PAM4 project, along with an Implementation Agreement (IA) document (Oif2017.346.07).

IEEE P802.3ck (100 Gb/s, 200 Gb/s, and 400 Gb/s Electrical Interfaces Task Force) is currently developing 100 Gb/s per lane electrical interfaces for chip-to-module, chip-to-chip, electrical backplane, and copper cable, for 100 Gb/s, 200 Gb/s, and 400 Gb/s Ethernet. The meeting materials from our Jan, 2019 interim meeting can be found at: http://www.ieee802.org/3/ck/public/19_01/index.html.

The IEEE P802.3ck Task Force is targeting to adopt baseline specifications by the May, 2019 meeting. We intend to communicate our future progress to you.

1 This document solely represents the views of the IEEE 802.3 Working Group, and does not necessarily represent a position of the IEEE, the IEEE Standards Association, or IEEE 802.
Sincerely,

David Law
Chair, IEEE 802.3 Ethernet Working Group